



DB2L33400L1

For rectification

■ Features

- Average Forward Current $I_F(AV) \leq 0.5$ A rectification is possible
- Low Forward Voltage
- High power capability due to Chip Size Package
 RoHS compliant (EU RoHS / MSL:Level 1 compliant)

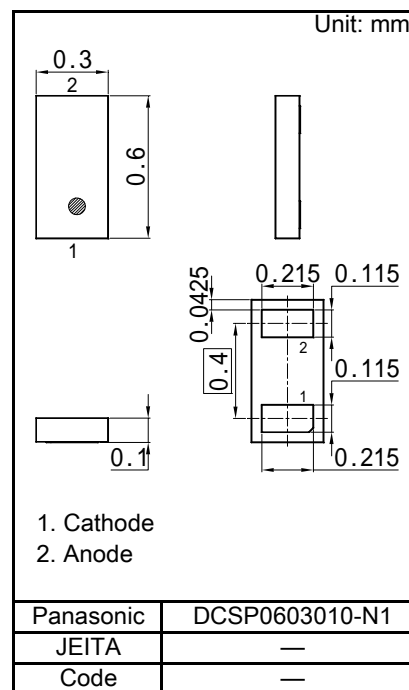
■ Marking Symbol: C5

■ Packaging

Embossed type (Thermo-compression sealing) : 1 000 pcs / reel (standard)

■ Absolute Maximum Ratings

Parameter	Symbol	Min	Max	Unit
Reverse Voltage ^{*1}	VR	-	30	V
Maximum Peak Reverse Voltage ^{*1}	VRM	-	30	V
Average Forward Current ^{*2,3}	$I_F(AV)$	-	0.5	A
Average Forward Current ^{*2,4}	$I_F(AV)$	-	0.5	A
Non-repetitive Peak Surge Forward Current ^{*1,5}	IFSM	-	5	A
Operating Junction Temperature ^{*6}	Tj	-	150	°C
Ambient Temperature	Ta	-40	+150	°C
Storage Temperature	Tstg	-55	+150	°C



Note) *1: Ta = Tj = 25°C

*2: Squire wave : $\sigma = 0.5$

*3: Ta $\leq 82^\circ\text{C}$, when device mounted on a FR4 PCB (25.4mm×25.4mm, 1mm thick), copper wiring (108mm² area, 36 μm thick).

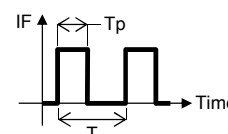
*4: Tsp $\leq 138^\circ\text{C}$

*5: Squire wave : Tp = 5 ms

*6: Power derating is necessary so that Tj < 150°C.

(Waveform definition)

$$\text{Duty Cycle : } \sigma = \frac{T_p}{T}$$



■ Electrical Characteristics Ta = 25 °C ± 3 °C

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Forward Voltage	VF	IF = 0.5 A	-	0.45	0.54	V
Reverse Current	IR	VR = 30 V	-	10	45	μA
Terminal Capacitance	Ct	VR = 10 V, f = 1 MHz	-	10	-	pF
Reverse Recovery Time ^{*1}	trr	IF = IR = 100 mA, I _{rr} = 10 mA	-	3.5	-	ns

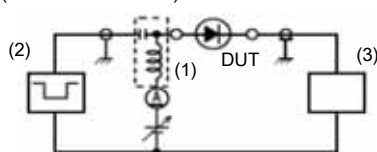
Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.

2. This product is sensitive to electric shock (static electricity, etc.).

Due attention must be paid on the charge of a human body and the leakage of current from the operating equipment.

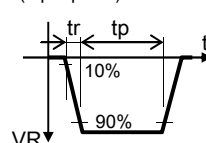
3. *1: Measurement circuit, input pulse, output pulse for Reverse recovery time

(Measurement circuit)



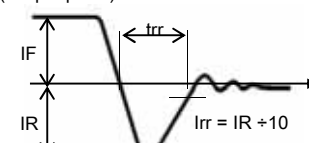
- (1) Bias Insertion Unit (N-50BU)
- (2) Pulse Generator (PG-10N), RS = 50 Ω
- (3) Wave Form Analyzer (SAS-8130), Ri = 50 Ω

(Input pulse)



- tp = 2 μs
- tr = 0.35 ns
- $\sigma = 0.05$

(Output pulse)

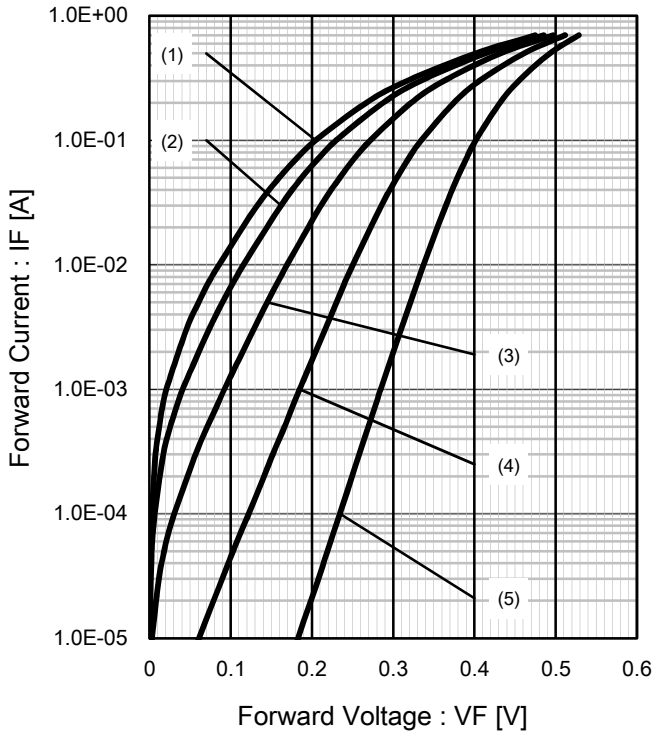


- IF = 100 mA
- IR = 100 mA
- I_{rr} = 10 mA

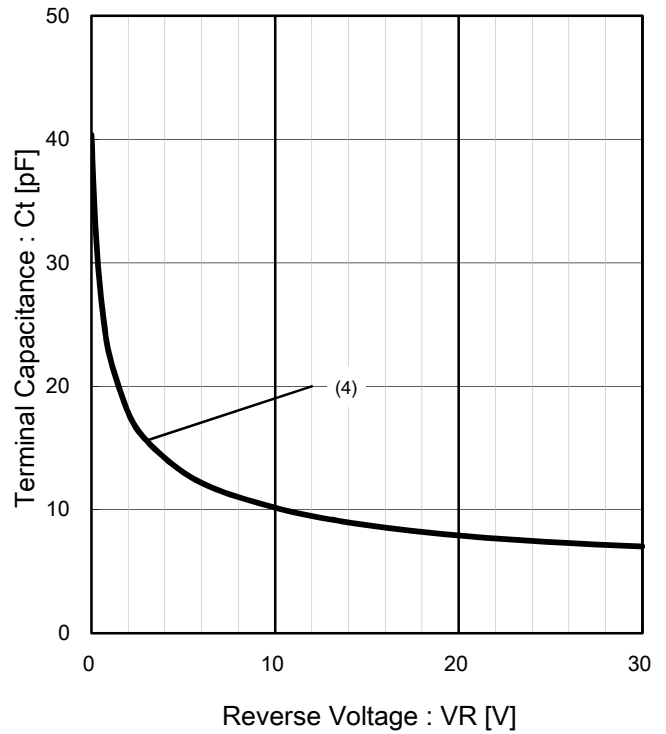


Electrical Characteristics Technical Data (Reference)

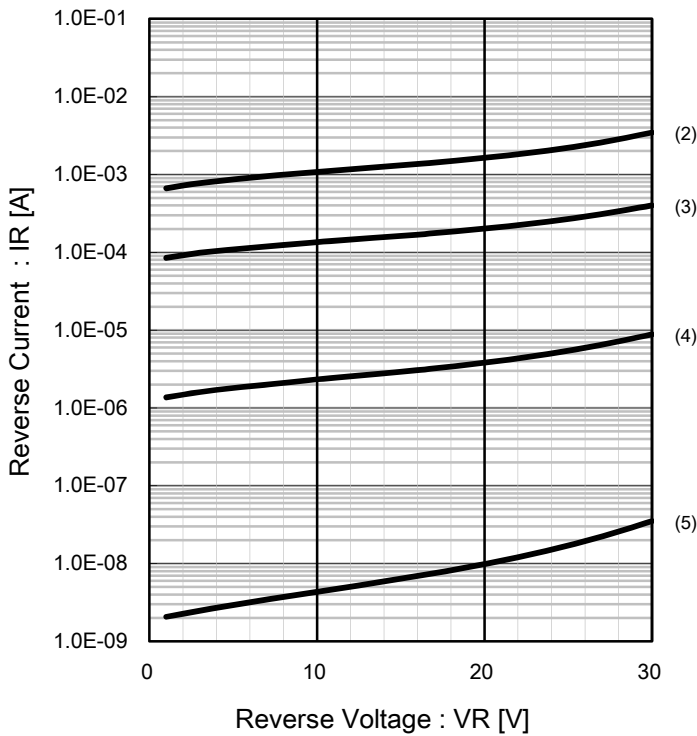
IF - VF / Typical Data



Ct - VR / Typical Data



IR - VR / Typical Data



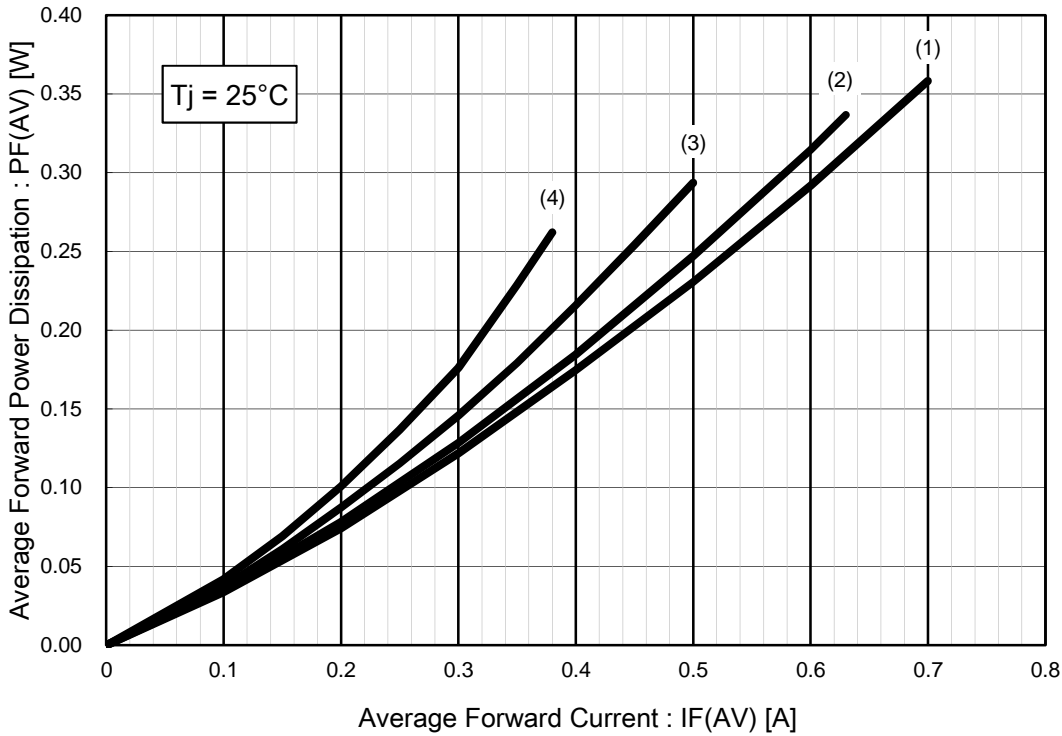
(Graph legends)

(1)	Ta = 150 °C
(2)	Ta = 125 °C
(3)	Ta = 85 °C
(4)	Ta = 25 °C
(5)	Ta = -40 °C

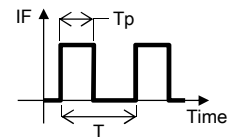


Electrical Characteristics Technical Data (Reference)

PF(AV) - IF(AV) / Typical Data



(Waveform definition)

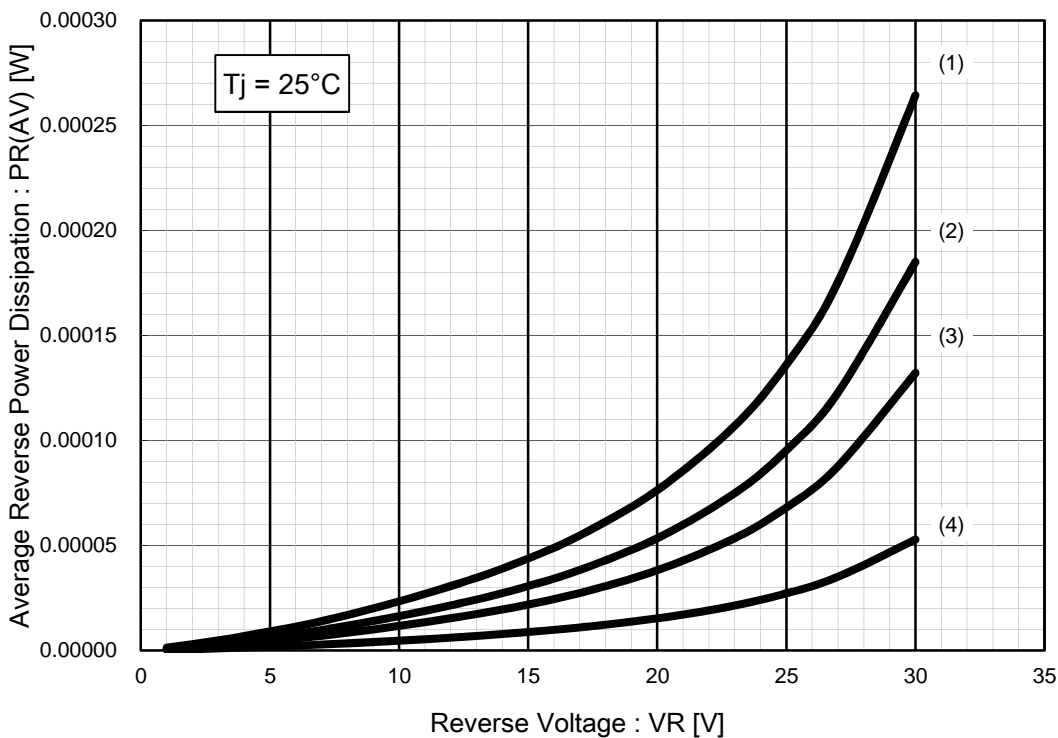


$$\text{Duty Cycle : } \sigma = \frac{T_p}{T}$$

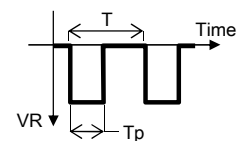
(Graph legends)

(1)	$\sigma = 1.0$
(2)	$\sigma = 0.8$
(3)	$\sigma = 0.5$
(4)	$\sigma = 0.3$

PR(AV) - VR / Typical Data



(Waveform definition)



$$\text{Duty Cycle : } \sigma = \frac{T_p}{T}$$

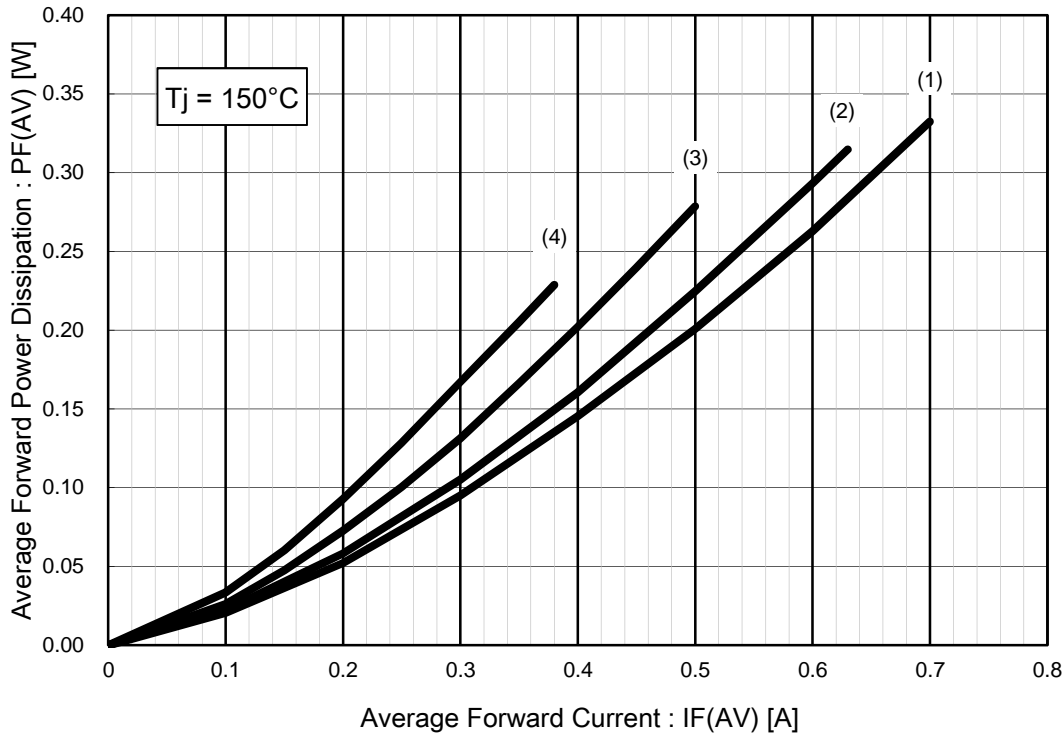
(Graph legends)

(1)	$\sigma = 1.0$
(2)	$\sigma = 0.7$
(3)	$\sigma = 0.5$
(4)	$\sigma = 0.2$

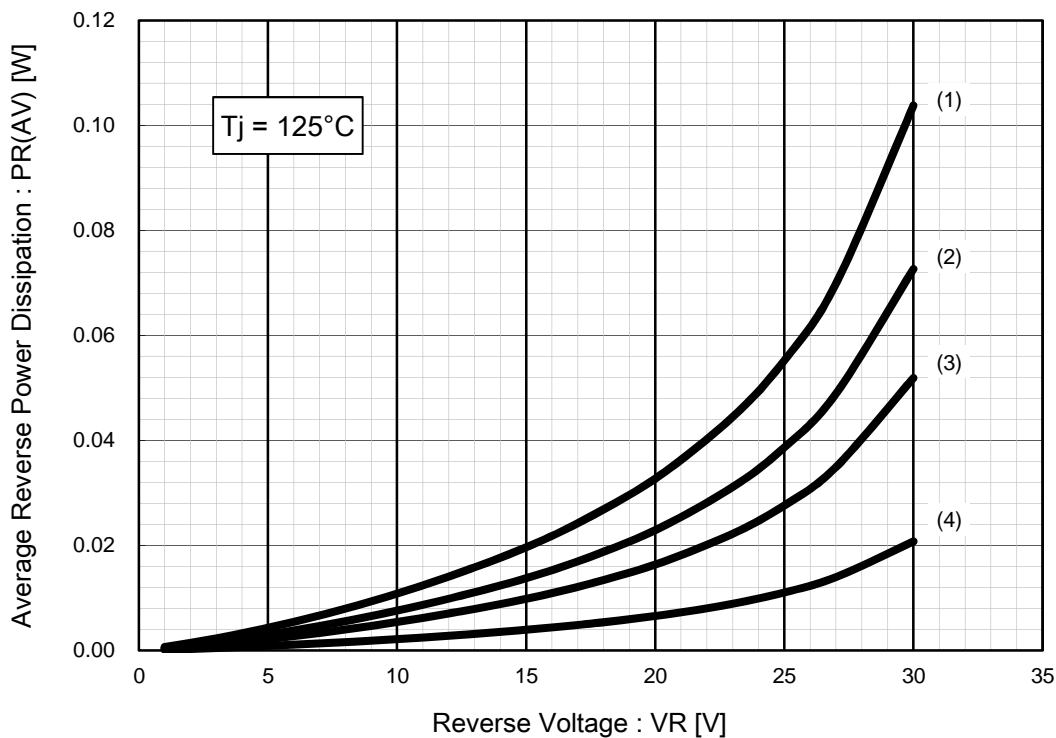


Electrical Characteristics Technical Data (Reference)

PF(AV) - IF(AV) / Typical Data



PR(AV) - VR / Typical Data

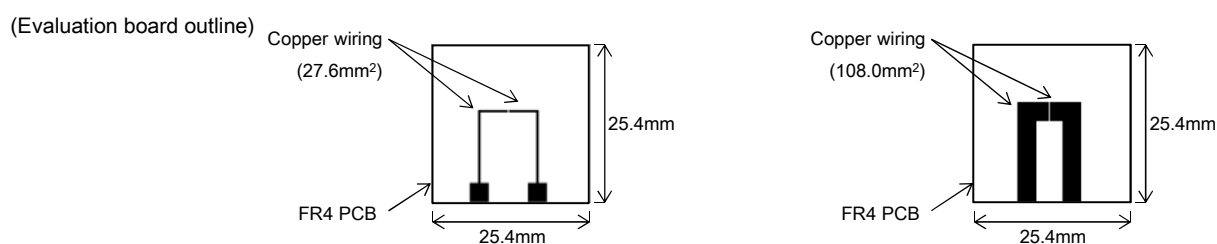




■ Thermal Characteristics

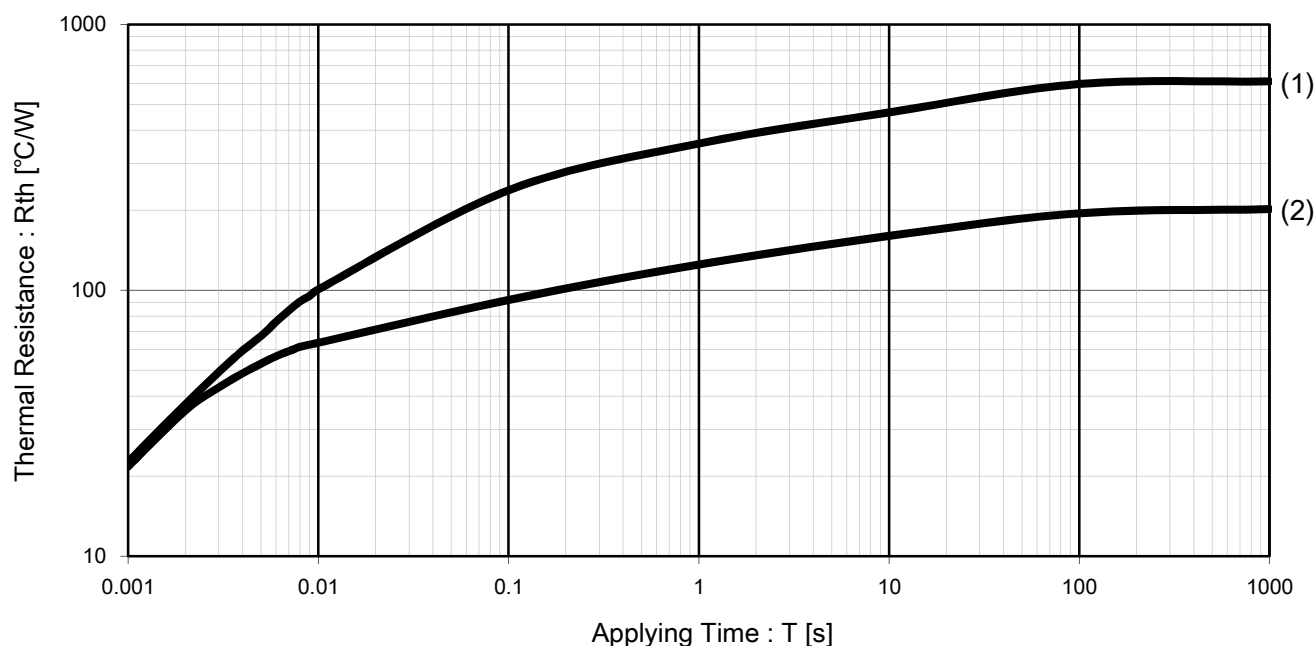
Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Thermal Resistance, Junction to Solder Point	$R_{th(j-sp)}$	$T_a = 25^\circ\text{C}$, in free air	-	35	-	$^\circ\text{C/W}$
Thermal Resistance, Junction to Ambient *1	$R_{th(j-a)}$	$T_a = 25^\circ\text{C}$, in free air	-	610	-	$^\circ\text{C/W}$
Thermal Resistance, Junction to Ambient *2	$R_{th(j-a)}$	$T_a = 25^\circ\text{C}$, in free air	-	202	-	$^\circ\text{C/W}$

Note) *1: Device mounted on a FR4 PCB (25.4mm×25.4mm, 1mm thick), copper wiring (27.6mm² area, 36μm thick).
 *2: Device mounted on a FR4 PCB (25.4mm×25.4mm, 1mm thick), copper wiring (108.0mm² area, 36μm thick).

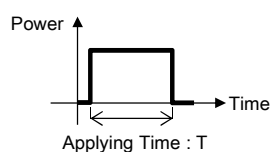


Thermal Characteristics Technical Data (Reference)

$R_{th} - T^{*1}$ / Typical Data



Note) *1: Single pulse measurement
 (Waveform definition)



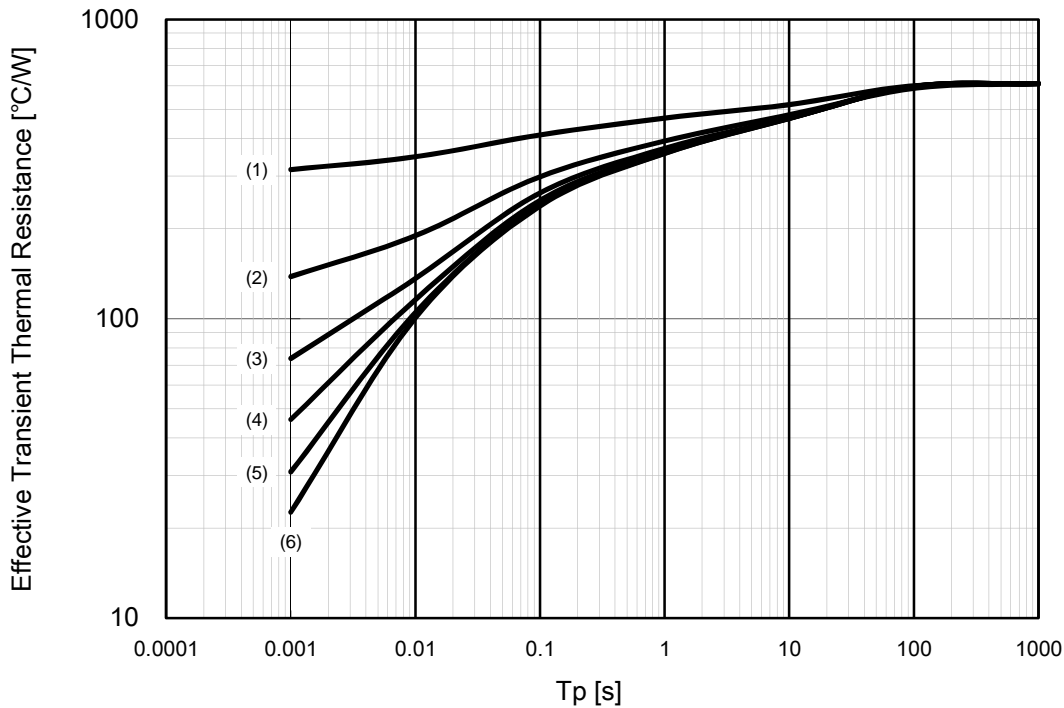
(Graph legends)

(1)	Device mounted on a FR4 PCB (25.4mm×25.4mm, 1mm thick), copper wiring (27.6mm ² area, 36μm thick).
(2)	Device mounted on a FR4 PCB (25.4mm×25.4mm, 1mm thick), copper wiring (108.0mm ² area, 36μm thick).

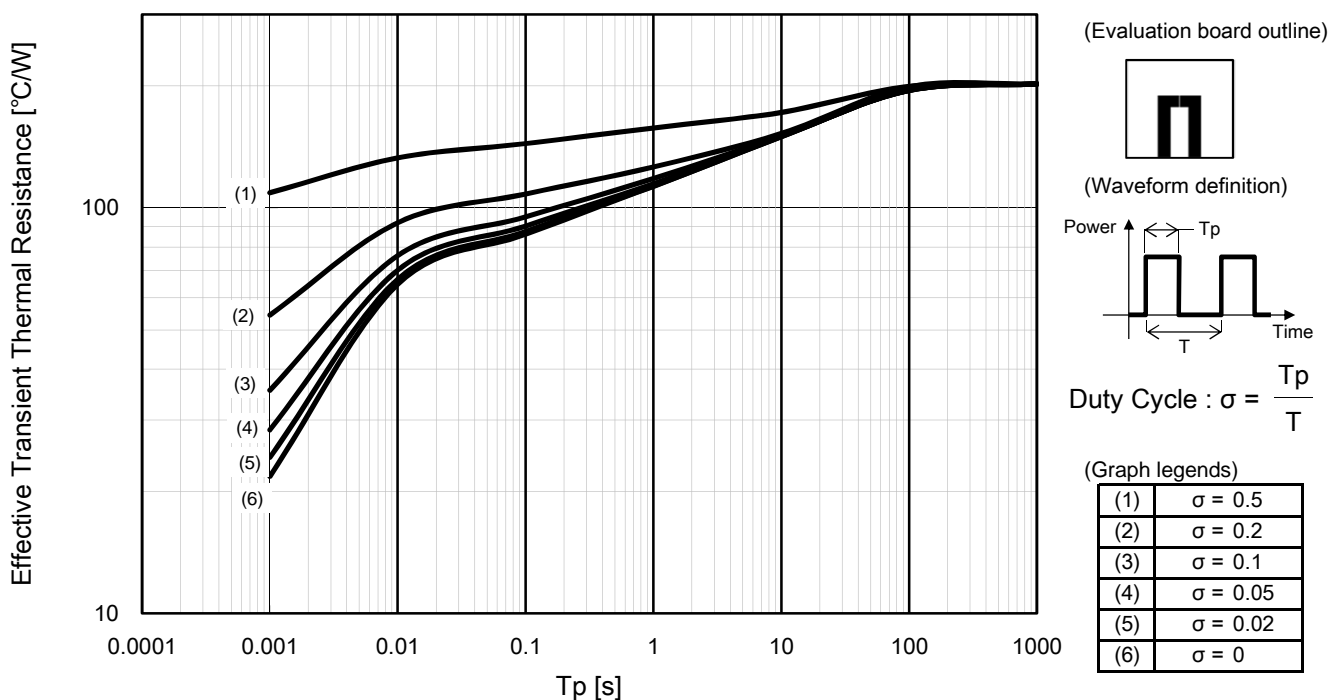


Thermal Characteristics Technical Data (Reference)

Effective Transient Thermal Resistance - T_p^{*1} / Typical Data



Effective Transient Thermal Resistance - T_p^{*2} / Typical Data



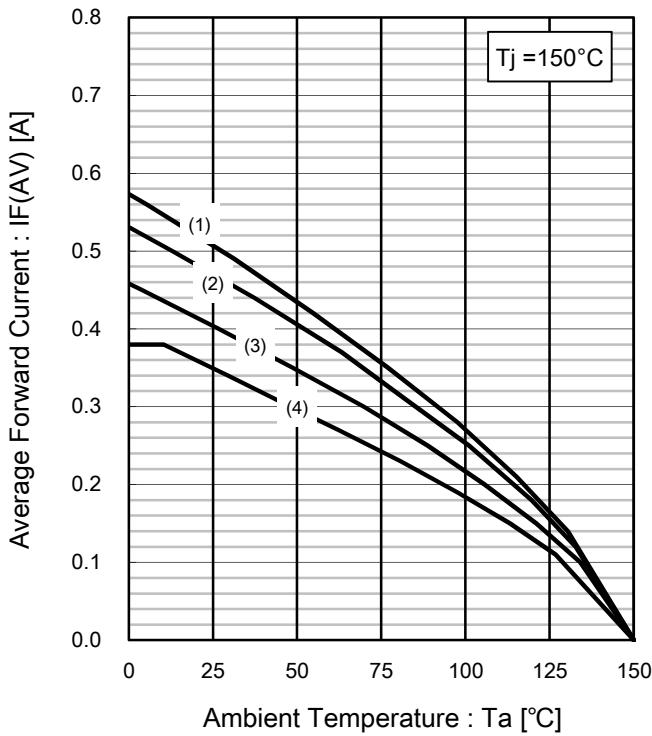
Note) *1: Device mounted on a FR4 PCB (25.4mm×25.4mm, 1mm thick), copper wiring (27.6mm² area, 36μm thick).

*2: Device mounted on a FR4 PCB (25.4mm×25.4mm, 1mm thick), copper wiring (108.0mm² area, 36μm thick).

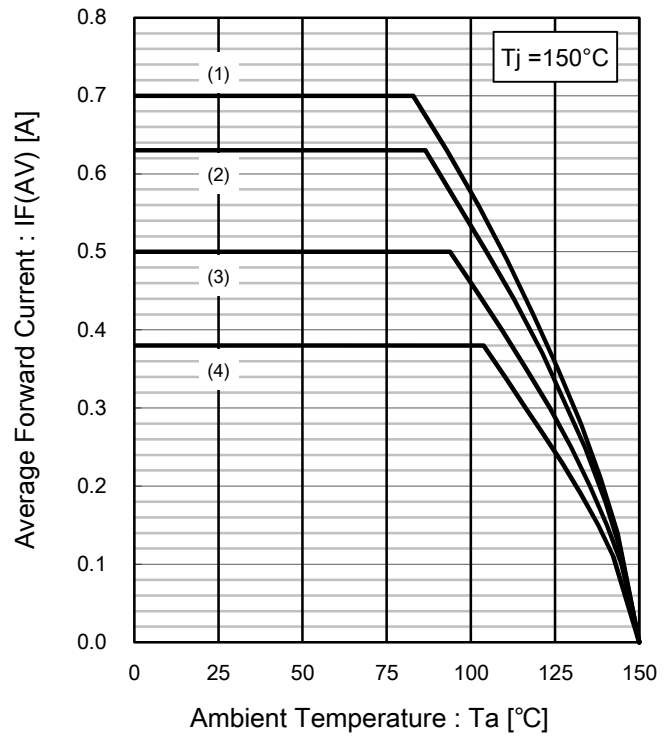


Power Derating Technical Data (Reference)

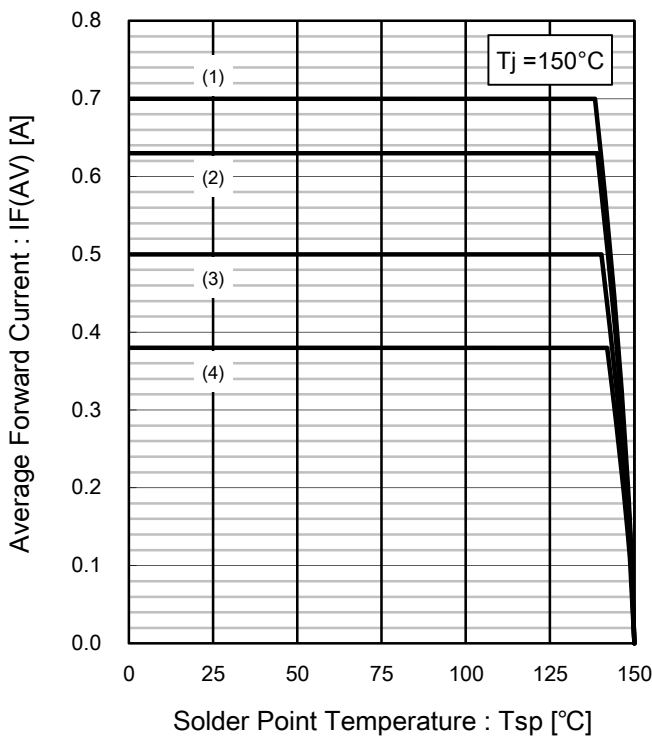
IF(AV) - Ta^{*1} / Typical Data



IF(AV) - Ta^{*2} / Typical Data



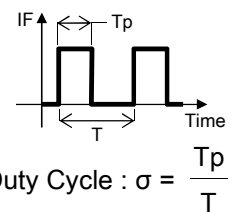
IF(AV) - Tsp / Typical Data



(Graph legends)

(1)	$\sigma = 1.0$
(2)	$\sigma = 0.8$
(3)	$\sigma = 0.5$
(4)	$\sigma = 0.3$

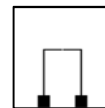
(Waveform definition)



Note)

*1: Device mounted on a FR4 PCB (25.4mm×25.4mm, 1mm thick), copper wiring (27.6mm² area, 36μm thick).

(Evaluation board outline)



*2: Device mounted on a FR4 PCB (25.4mm×25.4mm, 1mm thick), copper wiring (108.0mm² area, 36μm thick).

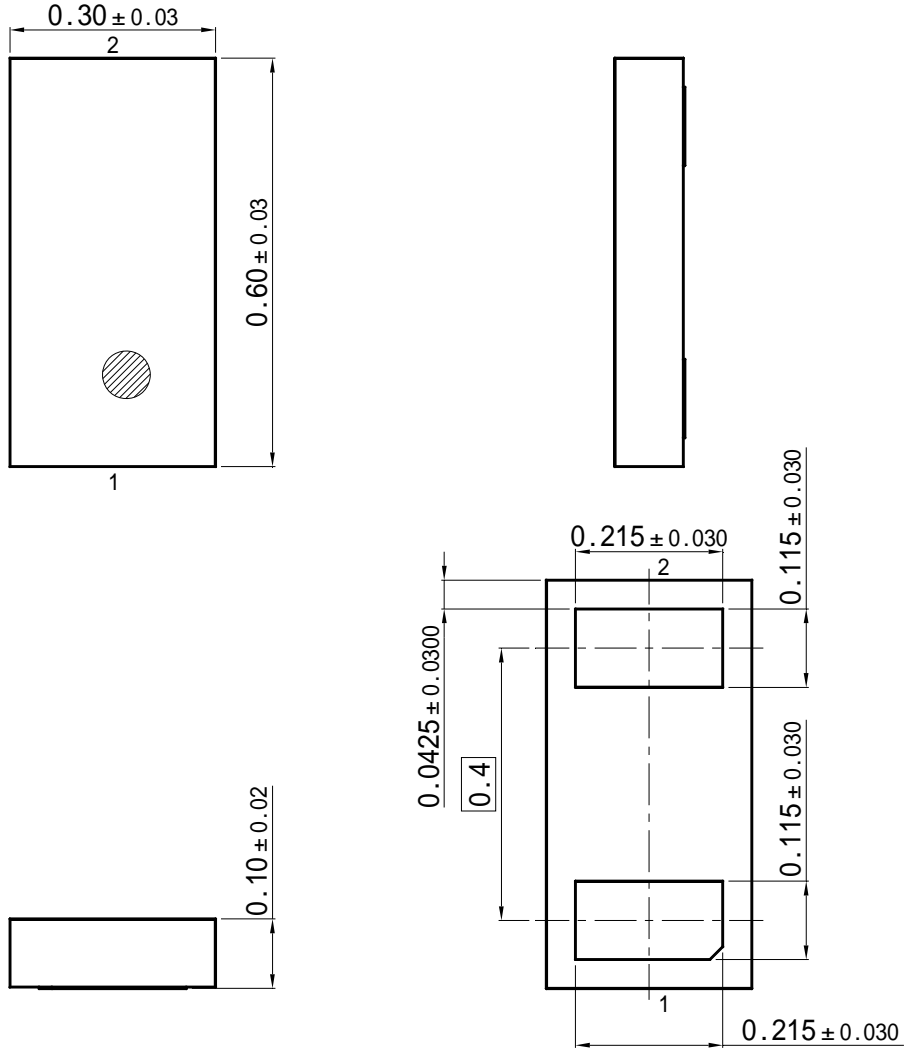
(Evaluation board outline)





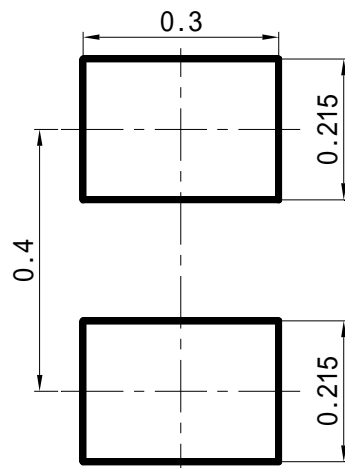
DCSP0603010-N1

Unit: mm



■ Land Pattern (Reference)

Unit: mm



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